# Product Specification

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| Product: | **Filler Conductive Silver Paste** |
| Part Number: | **01H-5901** |

## Application Scope :

This product is designed for use in ceramic circuit fillers, including LTCC and LED applications.

## Usage Conditions :

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| Substrate | Ceramic circuit |
| Printing | Screen printing |
| Leveling | Let it level at room temperature for 5-15 minutes (adjust time based on actual leveling conditions). |
| Drying | Bake in a ventilation oven at 100-150°C for 10-15 minutes (the test temperature should not exceed 300°C; the baking time may be adjusted based on actual conditions). |
| Firing Condition | The sintering is carried out in air atmosphere, the maximum temperature is 600~900°C (recommended value), and the sintering time is 10 minutes. |
| Thinner | ST-1000 |

## Characteristics :

### 1. Paste Characteristics :

| Characteristic | | Standard | Test Method And Conditions |
|---|---|---|---|
| 1 | Fineness | ≤5μm | FOG test |
| 2 | Viscosity | 200-580Pa.s | Brookfield HBT (Boli Fei) viscometer, rotor model SC4-14/6R, operating at 10rpm and 25±1°C, with adjustable viscosity according to user requirements. |

### 2. Characteristics After Curing :

Under the 1-sintering condition, the film thickness is 8-12 μm.
Check fired film produced under the conditions specified in 1）, (Film thickness is 8-12μm.)

| Characteristics | | Standard | Test Method And Conditions |
|---|---|---|---|
| 3 | Resistivity | ≤5mΩ/□ | Test pattern 0.6mm×60mm |

**Save Conditions And Validity Period :**

The product shall be stored in a sealed container at an ambient temperature of 5-25°C, with a shelf life of 1 year from the date of shipment.

**Packaging Method :**

Standard packaging, 1000g/can; samples are available in 200g small can packaging.